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10/20/01

TJK/182/L.W.

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of Soon-Bin JUNG et al.) HIGH DENSITY PLASMA PROCESSING
Korean Appln. No. 2000-32869) APPARATUS
Korean Filing Date: June 15, 2000)

PRELIMINARY AMENDMENT

Assistant Commissioner for Patents
Washington, D.C. 20231

Dear Sir:

Please amend the subject application as follows:

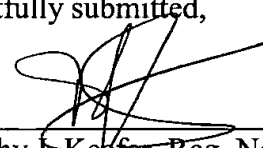
CROSS REFERENCE TO RELATED APPLICATION

This application claims the priority of Korean patent application Serial No. 2000-32869

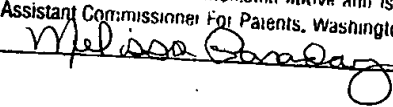
filed on June 15, 2000.

Respectfully submitted,

Date: 6/15/01
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By: 
Timothy J. Keffer, Reg. No. 35567

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